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<b>Bulletin Date:</b> 12/11/2014		<b>Bulletin Effective Date:</b> 12/11/2014	
<b>Title:</b> EFM32GG900 Datasheet Revision Notification			
<b>Originator:</b> Ted Batey		<b>Phone:</b> 512-532-5279	<b>Dept:</b> Marketing
<b>Customer Contact:</b> Kathy Haggart		<b>Phone:</b> 512-532-5261	<b>Dept:</b> Sales
<b>Bulletin Details</b>			
<b>Description:</b> Silicon Labs is pleased to announce version 1.1 of the EFM32GG900 Giant Gecko wafer sale datasheet is now available. This revision updates section 3.4 Bonding Instructions with a recommendation to use gold bond wires. An Environmental section (3.5.1) has also been added which discusses potential bare die sensitivity to ambient light.			
<b>Reason:</b> This bulletin recommends that customers purchasing wafers and designing their own packages use gold bond wires. Customers using bare die also need to be aware of potential light sensitivity.			
<b>Product Identification:</b> EFM32GG900F512G-D-D1I EFM32GG900F1024G-D-D1I			
This change is considered a minor change which does not affect form, fit, function, quality, or reliability. The information is being provided as a customer courtesy.  Please contact your local Silicon Labs sales representative with any questions about this notification. A list of Silicon Labs sales representatives may be found at <a href="http://www.silabs.com">www.silabs.com</a>			
<b>Customer Actions Needed:</b> Review packaging and bonding design to ensure use of gold bond wires.			